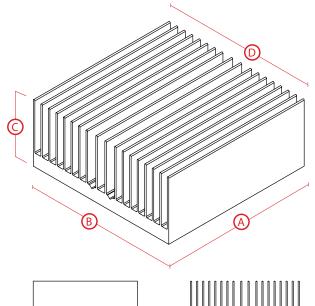


High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-54425W-C2-R0

Features & Benefits

- High aspect ratio, straight fin heat sinks that are ideal for » compact PCB environments
- Designed specifically for BGAs and other surface mount » packages
- Comes preassembled with high performance thermal » interface material



*Image above is for illustration purposes only.



Thermal Performance

AIR VELOCITY				THERMAL RESISTANCE		
FT/MIN		М	/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
	200 1.0		.0	2.2	1.3	
	300	1	.5	1.7		
	400	2	.0	1.4		
	500	2	.5	1.3		
	600	3	.0	1.2		
	700	3	.5	1.1		
	800	4	.0	1		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
42.5 mm	42.5 mm	24.5 mm	42.5 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES:

- 2) Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the 3) design or performance.
- 4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.gats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

Dimension C = heat sink height from bottom of the base to the top of the fin field.